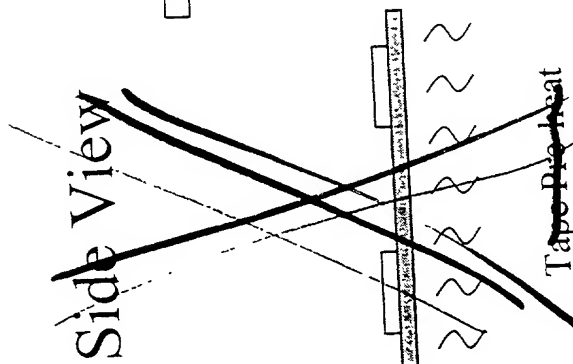
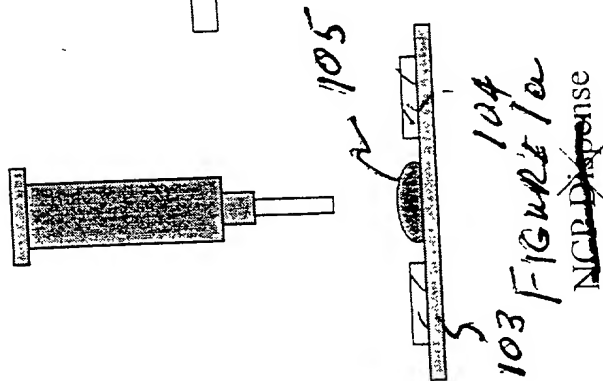
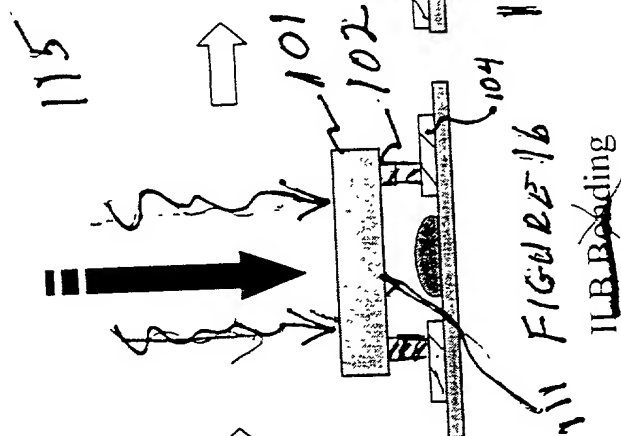
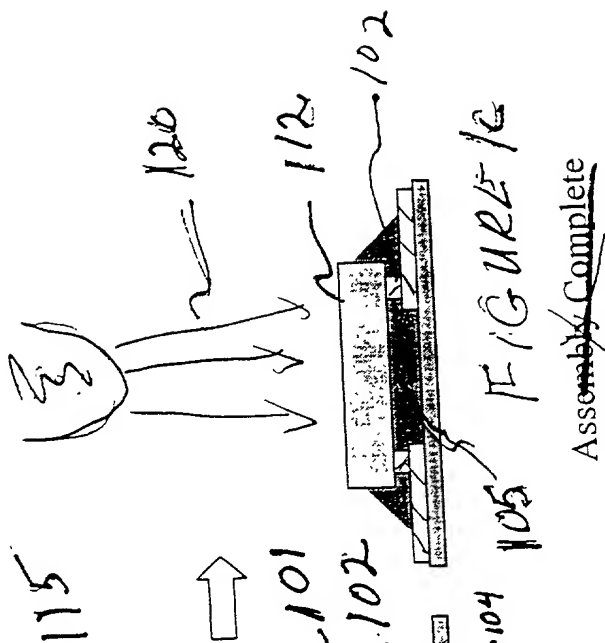
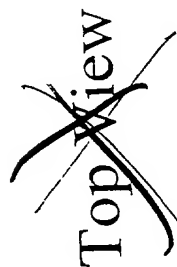
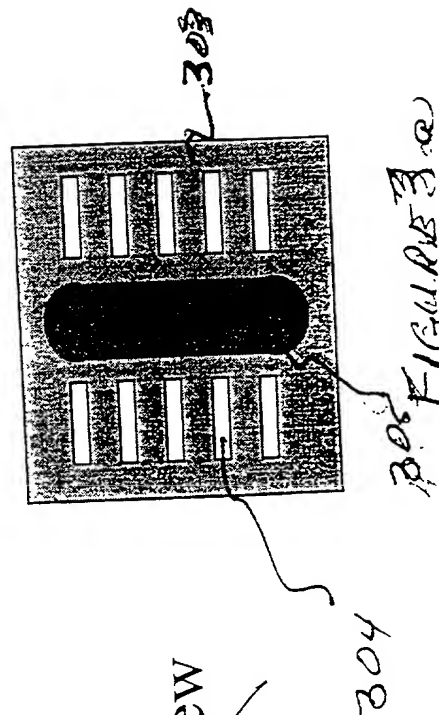
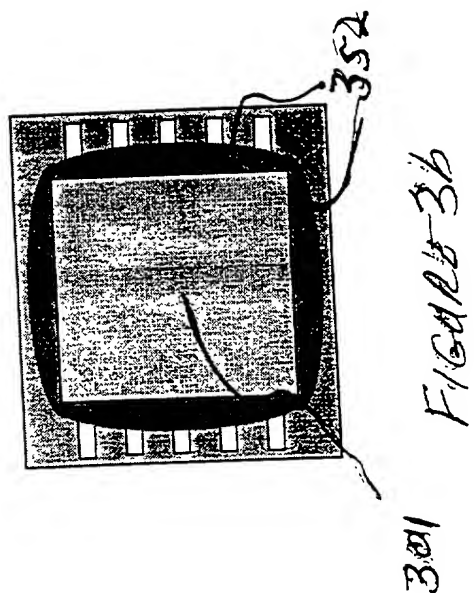


~~COF is a Reel-to-Reel Process~~

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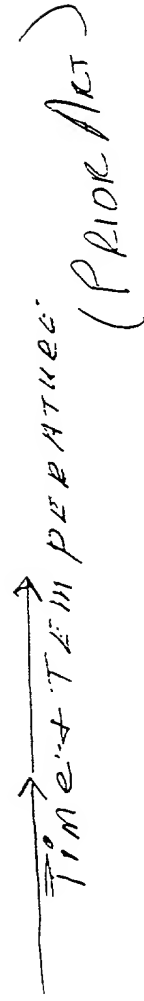
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FIGURE 2

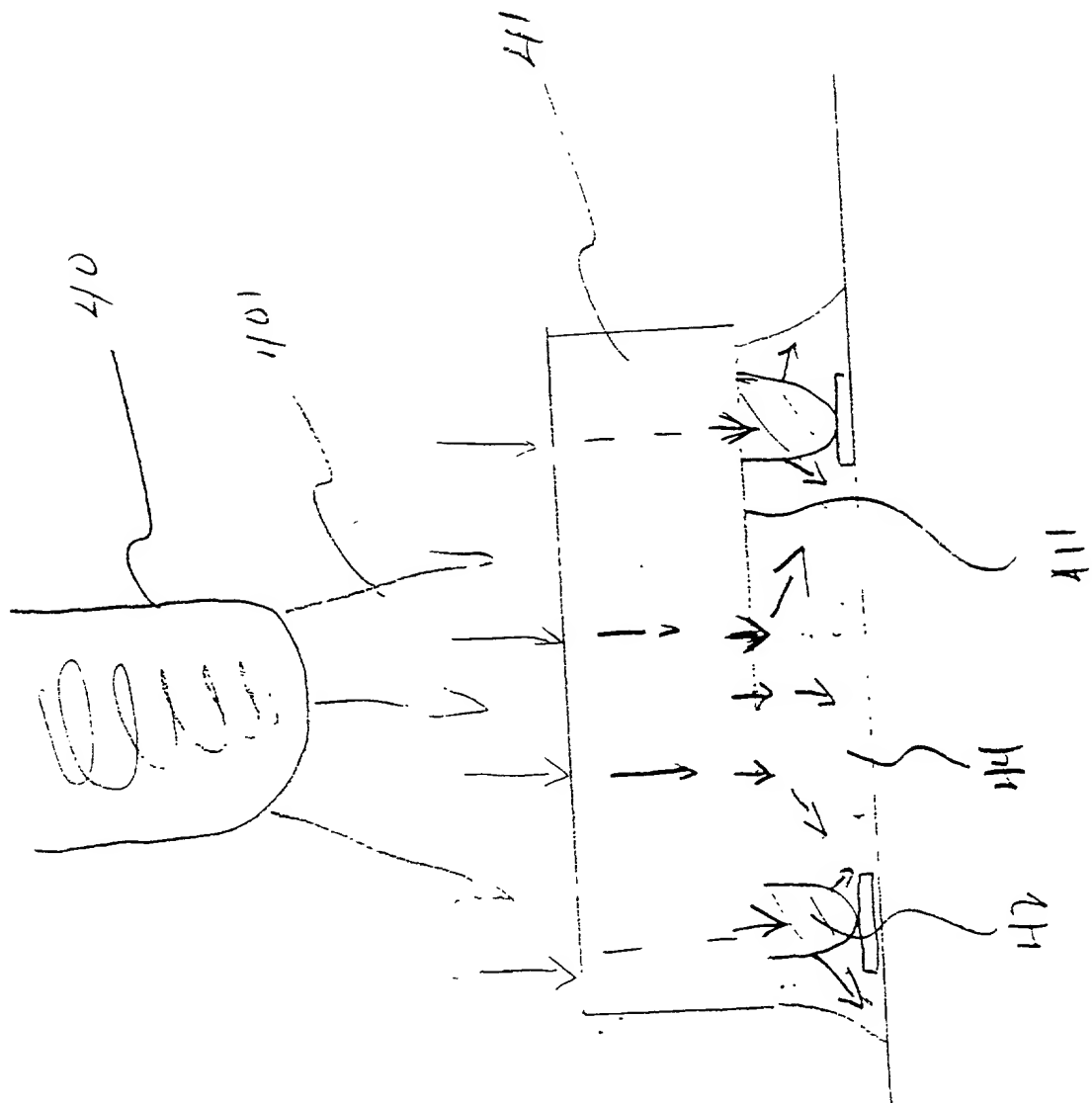
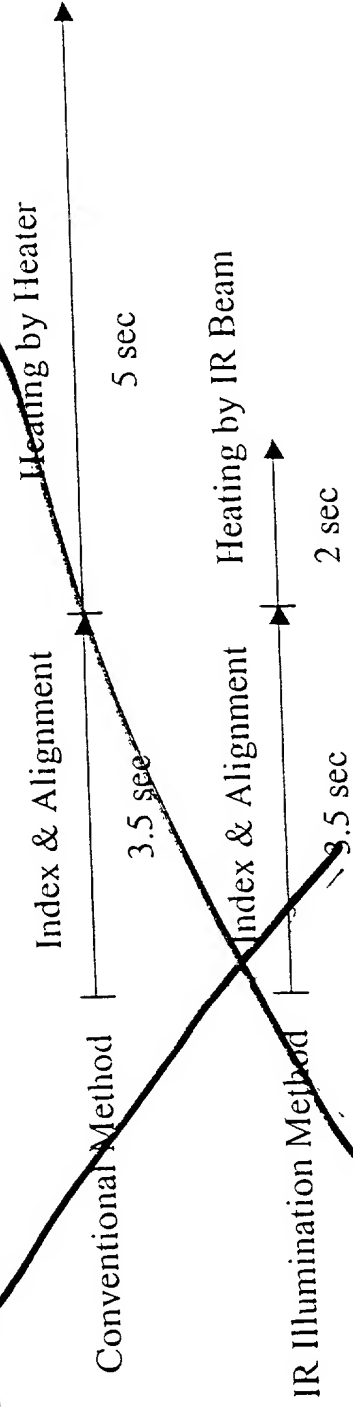


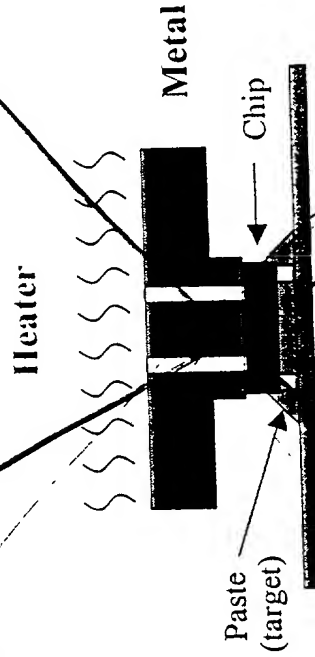
FIGURE 1

Improve 40% Total Cycle Time :



Principles :

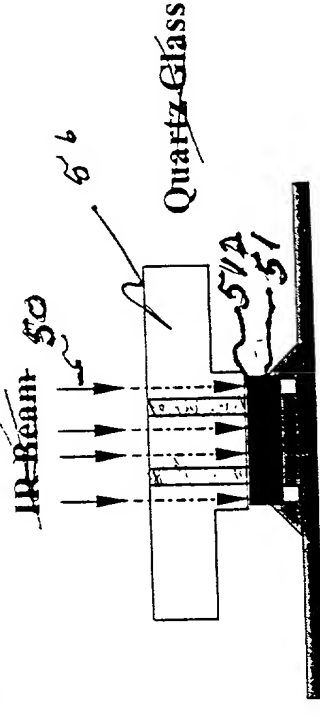
Conventional



Chip (silicon) is a low thermal conductivity interface. It takes time to transfer heat to target through silicon.

IR Illumination

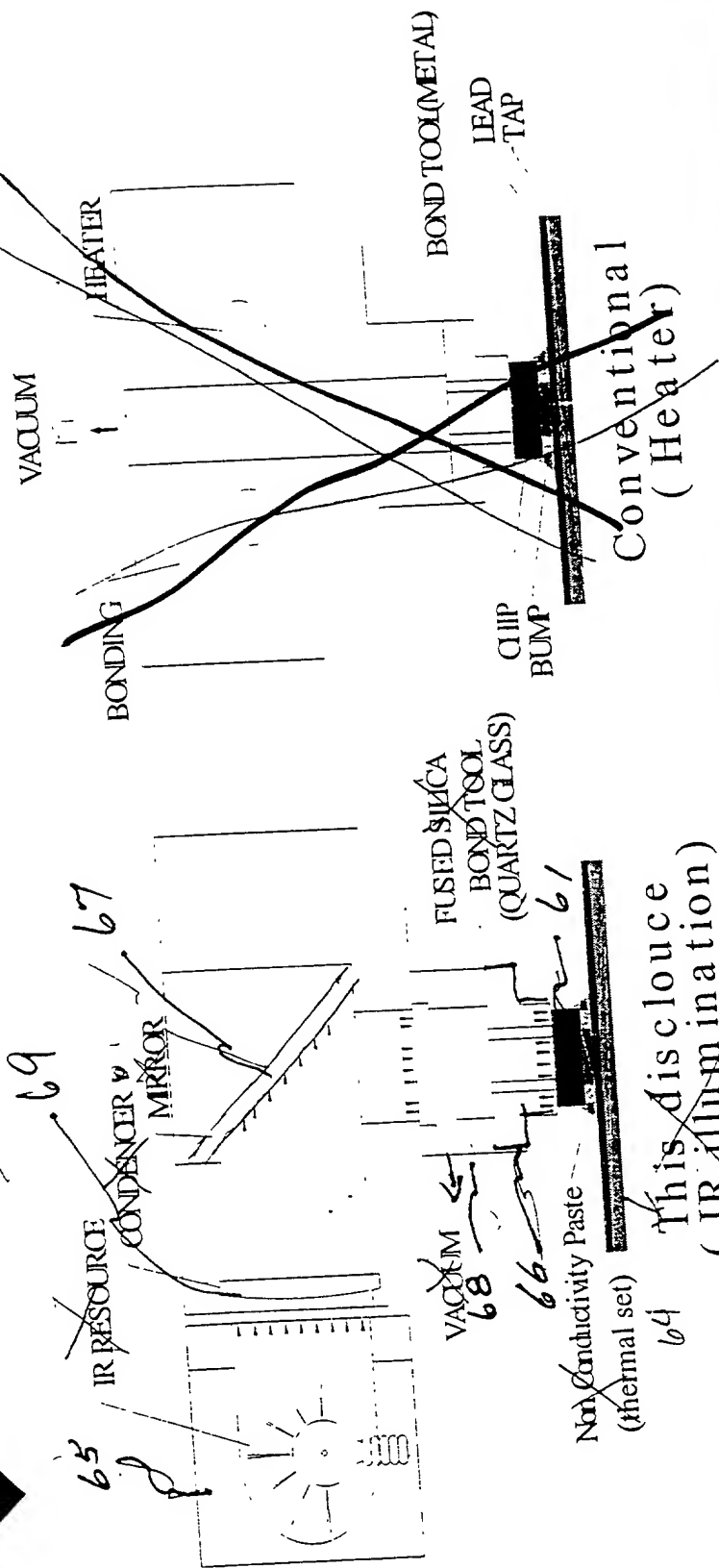
FIGURE 5



Quartz glass with 60% transmission rate by IR beam. Heating energy of IR illumination can be absorbed by epoxy easily to reduce heating time.

TI-32608

TI Taiwan 2000 Annual Policy Deployment
~~CONFIDENTIAL~~ Bond Heating Method



This disclosure
 (IR illumination)

FIGURE 6

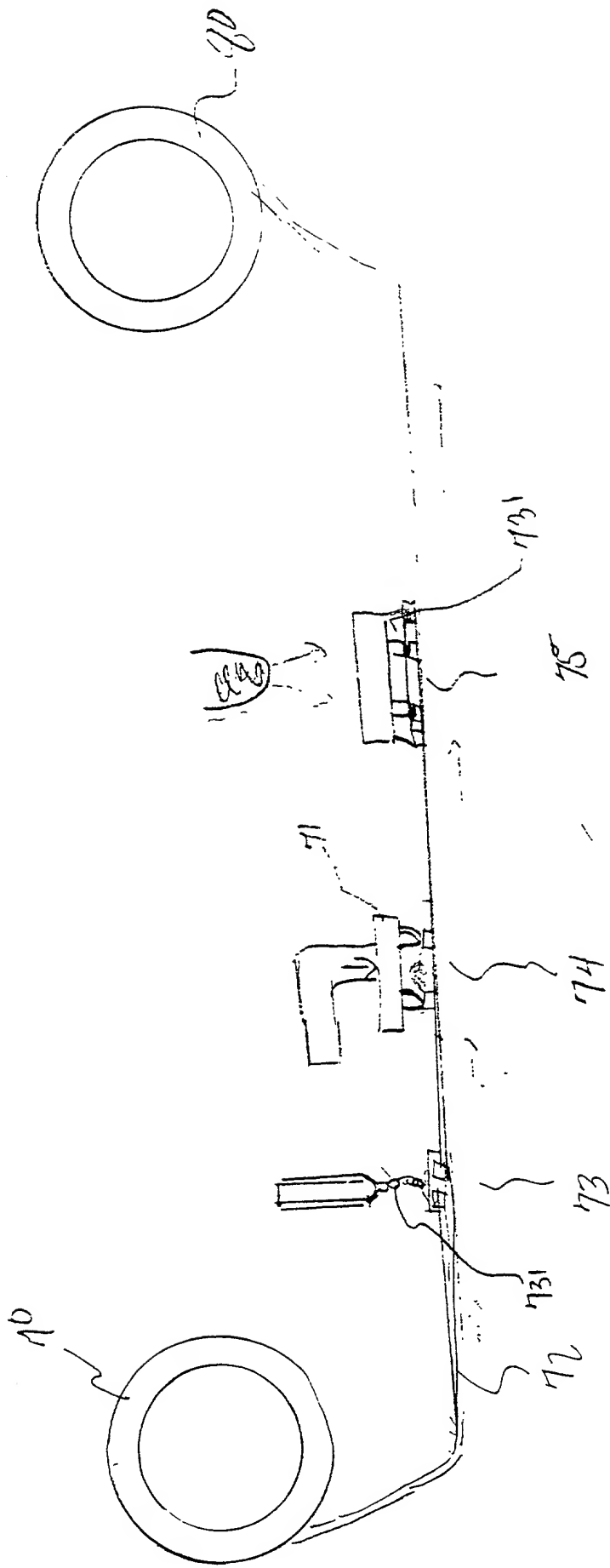


Fig 7